Safe Harbor Statement

This presentation may contain forward-looking statements about the Company including, without limitation, benefits and performance expected from use of the Company’s 1T-SRAM®, 1T-FLASH™, and mixed-signal technologies. Forward-looking statements are based on certain assumptions and expectations of future events that are subject to risks and uncertainties. Actual results and trends may differ materially from historical results or those projected in any such forward-looking statements depending on a variety of factors. These factors include but are not limited to, customer acceptance of our 1T-SRAM, 1T-FLASH, and mixed-signal technologies, the timing and nature of customer requests for our services under existing license agreements, the level of commercial success of licensees’ products, ease of manufacturing and yields of devices incorporating our 1T-SRAM, our ability to enhance the 1T-SRAM, 1T-FLASH, and mixed-signal technology or develop new technologies, the level of intellectual property protection provided by our patents, the vigor and growth of markets served by our licensees and customers, and operations of the Company and other risks identified in the Company’s most recent annual report on Form 10-K filed with the Securities and Exchange Commission, as well as other reports that MoSys files from time to time with the Securities and Exchange Commission. MoSys undertakes no obligation to update publicly any forward-looking statement for any reason, except as required by law, even as new information becomes available or other events occur in the future.
MoSys (NASD: MOSY) Background

- World leader in SoC embedded memory IP
  - Over 150 million units shipped
- Product offering ranges from bit cell/patent license to complete sub-systems to turnkey mixed-signal SoCs
- 80+ worldwide customers. Proven IP methodology with >175 licenses
- 134 US/foreign memory patents issued, 59 applications pending
- Len Perham (CEO) joined Nov. ‘07. Previously IDT 86-00. Incubated MoSys, Centaur, Clear Logic, QED, Galileo Tech
- 200 employees—80% engineering (High-end Analog, DSP development, CPU-based SOCs, Firmware/Software)
- Sunnyvale, CA HQ with development and sales facilities in China, Korea, Europe
New Organization in Place Q1 2008

- **Executive Staff**
  - CEO, CFO, VP Sales

- **Worldwide Sales Team**
  - Reorganized
  - Regional support added: Taiwan, China, Europe

- **Marketing**
  - Added mixed-signal experience

- **Engineering**
  - Added additional Flash memory expertise
  - Analog/mixed-signal design teams
    - 50+ hardware engineers in Europe
    - 40+ hardware and firmware engineers in China

- **Senior Advisory Team**
  - Senior circuit design/device physics expert
  - Influential Pacific Rim business person
MoSys Foundation Technology

Embedded 1T-SRAM.
Dense.
High performance.
Portable.
Reliable.

Die Photo of AMD AM29X305ADC MCU for example only.
Customers/Products

MoSys® Memory and mixed-signal IP

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Analog Mixed-Signal Capability

- 2007 acquisition of Atmel’s Network Storage Products Group
- ~100 analog/mixed-signal & firmware developers
- New level of capability for the under served analog IP supply chain
- Adds flexible IP options for consumer and computing SoCs previously not readily available as IP

Silicon Verified IP:
- Optical storage (Blu-ray)
- High speed networking
- Serial connectivity
Company Focus

Increase SoC floor plan coverage by supplying the industry’s application optimized embedded memories/mixed-signal IP blocks through focus on high growth connected consumer, converged mobile, and embedded computing platforms.
MoSys Accelerating IP Availability

- Embedded NVM 1T-FLASH
- Blu-ray DVD Front End
- SATA II
- Hi-Resolution 1T-SRAM Display Driver IC
- Gigabit Ethernet PHYs
- Embedded 1T-SRAM

Die Photo of AMD AM29X305ADC MCU for example only.
1T-SRAM Customer Value Proposition

- Reduce ASP
- Increase Memory
- Add Logic

6T Embedded SRAM

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1T-SRAM Summary

- Wii™ Proven...
- Over 150 million devices shipped in leading game consoles, handsets, networking, and consumer devices
- Up to 3 times denser than 6T-based designs
  - Enables breakthrough SoC performance
- Portable across multiple foundries & IDMs
- Highly Scalable
  - Available from 0.25-micron to 65nm. 55nm/40nm in development.
- Easy to Manufacture
  - Leverages basic CMOS logic process flow
- High Reliability
  - Qualified at multiple foundries and IDMs
  - TEC™ Error Correction Circuitry
1T-SRAM DDI Value Proposition

- Our first System Solution Macro!
- Lower cost
  - Reduce display driver frame buffer 20 to 50% vs. 6T
  - Built-in ECC versus external repair maximizes yield
  - Eliminate display bridge chips
- Longer battery life
  - App processor can be shutdown by moving the frame buffer memory into the driver chip in active idle mode
- Minimized height
  - 20:1 or better aspect ratio allows IC to fit under display bezel
- Reduced EMI
  - Minimize traffic between main board & display driver IC during idle mode
- Improved image quality by not requiring compression
High Resolution Mobile Phone and Personal Media Player Display Forecast Units ≥HVGA Resolution ≤4.3” Diagonal Screen Size 2007 to 2012

Source: DisplaySearch April 2008
1T-SRAM DDI Summary

- Mobile Internet Devices will accelerate demand for larger resolution displays
- 1T-SRAM DDI enables embedding larger memory densities in display driver ICs (from 3.5Mb to over 11Mb)
- Meets tight height & width requirements enabling frame buffer on glass
- Silicon proven and available
- In production in LG’s first AMOLED mobile phone
1T-FLASH Embedded Non-Volatile Memory
1T-FLASH™

- Uses standard CMOS logic processes with *no additional mask steps*
  - Leading competitor uses minimum of 8 additional masks
- Optimized for high-performance and density
- Scalable to advanced process geometries
  - Today have silicon in .25, .18, .13-micron & 65nm
  - In three foundries today
- Initial 0.13-micron characterization and qualification complete--silicon verified by June!
- Targeting microcontrollers with embedded FLASH requiring:
  - Up to 15K endurance cycles
  - 10 year data retention
  - Up to 125C operating range
  - Optimized for 64kb to 32Mb
## Typical Embedded Flash Applications

<table>
<thead>
<tr>
<th>Market</th>
<th>Application</th>
<th>8-bit</th>
<th>16-bit</th>
<th>32-bit</th>
<th>Flash Range</th>
</tr>
</thead>
<tbody>
<tr>
<td>Automotive</td>
<td>Various</td>
<td>X</td>
<td>X</td>
<td>X</td>
<td>16KB to 2MB</td>
</tr>
<tr>
<td>Industrial</td>
<td>Large appliances</td>
<td>X</td>
<td>X</td>
<td>X</td>
<td>60KB to 512KB</td>
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<tr>
<td></td>
<td>Small appliances</td>
<td>X</td>
<td>X</td>
<td></td>
<td>128KB</td>
</tr>
<tr>
<td></td>
<td>Remote control</td>
<td>X</td>
<td>X</td>
<td></td>
<td>32KB</td>
</tr>
<tr>
<td></td>
<td>Motor control</td>
<td>X</td>
<td>X</td>
<td></td>
<td>16KB</td>
</tr>
<tr>
<td></td>
<td>Point of sale</td>
<td></td>
<td></td>
<td>X</td>
<td>128KB</td>
</tr>
<tr>
<td></td>
<td>Industrial control</td>
<td></td>
<td></td>
<td>X</td>
<td>512KB</td>
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<tr>
<td></td>
<td>Sensors</td>
<td>X</td>
<td>X</td>
<td></td>
<td>8KB</td>
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<td></td>
<td>Electronic locks</td>
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<td></td>
<td>8KB</td>
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<td>Consumer Digital</td>
<td>Baseband chips</td>
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<td></td>
<td>X</td>
<td>224KB</td>
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<td>Mobile handsets</td>
<td>X</td>
<td>X</td>
<td>X</td>
<td>60KB</td>
</tr>
<tr>
<td></td>
<td>Camera phones</td>
<td></td>
<td></td>
<td>X</td>
<td>64KB</td>
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<td></td>
<td>Wireless authentication</td>
<td></td>
<td></td>
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<td>3.5KB</td>
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<tr>
<td></td>
<td>LCD driver</td>
<td></td>
<td></td>
<td>X</td>
<td>256KB</td>
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<tr>
<td></td>
<td>Optical disk controller</td>
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<td></td>
<td></td>
<td>768KB</td>
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<tr>
<td>Networking</td>
<td>Wireless</td>
<td>X</td>
<td>X</td>
<td></td>
<td>128KB</td>
</tr>
<tr>
<td></td>
<td>Wireless authentication</td>
<td></td>
<td></td>
<td>X</td>
<td>3.5KB</td>
</tr>
<tr>
<td></td>
<td>Indus. Network control</td>
<td></td>
<td></td>
<td>X</td>
<td>256KB</td>
</tr>
<tr>
<td>Office Automation</td>
<td>USB controllers</td>
<td>X</td>
<td></td>
<td></td>
<td>128KB to 1MB</td>
</tr>
<tr>
<td></td>
<td>Printers/copiers</td>
<td>X</td>
<td></td>
<td></td>
<td>384KB</td>
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<td>Smart Cards</td>
<td>Cell phone/SIM</td>
<td>X</td>
<td>X</td>
<td></td>
<td>36KB to 384KB</td>
</tr>
<tr>
<td></td>
<td>ID cards</td>
<td>X</td>
<td>X</td>
<td></td>
<td>4KB to 72KB</td>
</tr>
</tbody>
</table>
MoSys IP Offerings – Silicon Proven

**MOST3020 DVD SoC**
- Package: TEPBGA-2-300
- Foundry: Infineon 0.13
- Die size: 7.8 * 8 mm²
- Gate count: 2M
- Status: Silicon Proven

**MONW5320 PCI-E GbE NIC**
- Package: PBGA-208
- Foundry: TSMC 0.13
- Die size: 6.75*5.57 mm²
- Gate count: 5.3M
- Power: 2W
- Status: Design Ready

**MONW5320 PCI-E GbE NIC**
- Package: PBGA-208
- Foundry: TSMC 0.13
- Die size: 6.75*5.57 mm²
- Gate count: 5.3M
- Power: 2W
- Status: Design Ready

**MOCN5122 PCI-X to SATA Bridge**
- Package: PBGA-240
- Foundry: TSMC 0.13G
- Die size: 4.9*4.2 mm²
- Gate count: 1M
- Power: 300mW
- Status: Silicon Proven

**MONW7120 8 Port GbE Switch**
- Package: HSBGA484
- Foundry: TSMC 0.13LV
- Die size: 10.3*10.3 mm²
- Gate count: 10M
- Power: 7W
- Status: Silicon Proven

**MOCN5022 IDE to SATA Bridge**
- Package: QFP-64
- Foundry: TSMC 0.13G
- Die size: 2.4 * 2.5 mm²
- Gate count: 500K
- Power: 105mW
- Status: Silicon Proven
- Blu-ray DVD AV hardware to grow 100% year-over-year
- Blu-Ray DVD wins format war over HD-DVD!
  - Toshiba and Microsoft stop HD support
  - Movie studios and retailers now have clear path
  - Result: stronger growth now expected than with one primary format
- Market opportunity beyond major DVD & Blu-ray chip vendors
  - SoCs for connected consumer products: iP-DVD, iPTV, game consoles
  - Personal computers
- Complexity of design forces SoC suppliers to look for proven IP
Comprehensive Blu-ray DVD FE Solution

- Fusion 2™. Fully integrated hardware & firmware.
- Complete licensable 0.13-micron GDSII available
- Portable to foundries & IDMs at 65nm or 40nm
- Includes major analog/mixed-signal blocks*
  - PRML
  - High speed AD/DA converters
  - High speed/low-jitter PLLs
- Advanced DSP capability
- Deep support & customization services available
  - Integration, test and production bring-up
- Reference board available

*Available individually
GbEthernet Physical Layer IP

- Targeted for networking routers, switches, console gaming, PC motherboards...
- IEEE 802.3ab standards compliant Macro of Physical Layer Transceiver
- University of New Hampshire Interoperability Certified
- TSMC 0.13LV process IP available now
- Reference Board
Connectivity IP

- Targeted for hard disk drive based SoCs
- SATA MegaCell IP High Speed Interconnect
  - SATA PHY cores for Gen-I (1.5Gbs) and Gen-II (3.0Gbs)
  - SATA transport & link layer core
  - IDE-to-SATA and PC-X to SATA controller

- Mixed-Signal Macro IP Components
  - Hi-speed ADC and DACs, PLLs, etc.
  - PRML Read Channel for optical disc and hard disk drives
  - Hard disk drive controller core
From IP to Subsystems to Turnkey Analog SOCs

- 1T-SRAM
- 1T-FLASH (MTP to Mbytes)
- 1T-DDI
- BLU-Ray DVD PLATFORM
- BROADBAND CONNECTIVITY PLATFORM
- LCD PANEL PLATFORM
- SOLID-STATE STORAGE PLATFORM
- CUSTOM ANALOG SOCs

Patent Licensing
- Macro Licensing
- Chip GDSII Licensing
- Turnkey Analog SoC

SILICON FOUNDRIES and IDMs
Financial Overview
Financial & Operational Highlights March 31, 2008

- Total revenue of $2.8 million
- Increased royalty revenue 21% year-over-year
- $77 million in cash and investments
- Booked first foundry order for 1T-SRAM Display Driver IC IP
- Delivered first 1T-FLASH production macro
- Demonstrated fully functional Blu-ray analog/mixed-signal SoC
## Summary Income Statement (Non–GAAP*)
(In millions except per share amount)

<table>
<thead>
<tr>
<th></th>
<th>Q1 08</th>
<th>Full Year 2007</th>
<th>Q4 07</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Total Revenues</strong></td>
<td>$2.8</td>
<td>$14.3</td>
<td>$2.9</td>
</tr>
<tr>
<td><strong>Licensing</strong></td>
<td>0.4</td>
<td>5.2</td>
<td>0.4</td>
</tr>
<tr>
<td><strong>Royalty</strong></td>
<td>2.4</td>
<td>9.1</td>
<td>2.5</td>
</tr>
<tr>
<td><strong>Gross Profit</strong></td>
<td>2.3</td>
<td>12.1</td>
<td>2.3</td>
</tr>
<tr>
<td><strong>Margin %</strong></td>
<td>86%</td>
<td>85%</td>
<td>79%</td>
</tr>
<tr>
<td><strong>Op Ex</strong></td>
<td>6.3</td>
<td>20.0</td>
<td>6.5</td>
</tr>
<tr>
<td><strong>Non-GAAP Net Loss</strong></td>
<td>($2.8)</td>
<td>($3.4)</td>
<td>($3.2)</td>
</tr>
<tr>
<td><strong>EPS</strong></td>
<td>($0.09)</td>
<td>($0.11)</td>
<td>($0.10)</td>
</tr>
</tbody>
</table>

*Non-GAAP: excludes non-cash charges including stock-based compensation, IP R&D and amortization of acquired intangible assets
Summary

- Breadth of product offerings greatly expanded
  - Continued strength on 1T-SRAM IP
  - First 40nm 1T-SRAM macros in development
  - First major order from mixed-signal product line
  - Multiple customers evaluating Blu-ray DVD SoC IP
  - Imminent release of disruptive embedded Flash technology
- Expanding customer base with excellent reception for new products
- High gross margins with recurring royalty revenue model
- $77 million cash & investments—no debt
- New proven management team
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